

(19) Japanese Patent Office

(11) JP 08199062 A

(45) 19960806

(21) Application number: 07010888 (51) Int Cl.: C08L07700, B65D06500, B65D08124,
(22) Date of filing: 19950126 C08K00334

(54) POLYAMIDE MOLDING

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(57) PURPOSE: To obtain a polyamide molding which has excellent gas-barrier properties without detriment to the excellent toughness inherent in a polyamide resin.

CONSTITUTION: This molding is produced from a compsn. comprising a polyamide resin and a layered silicate microdispersed therein, and the molding satisfies the relations: $0.05 \leq A \leq 5$, $P \leq kA + N$, and $k = 0.0017N^2 - 0.43N + 0.14$ [wherein A is the ash content (wt.%) of the molding; P is the oxygen permeability (cc/day/m²/atm) per 25μm-thickness of the molding at 23°C under a relative humidity of 95%; and N is the value of P when A is 0].